

WET BENCH: OXIDE ETCH + HYDROPHILIC CLEAN (RCA CLEAN)

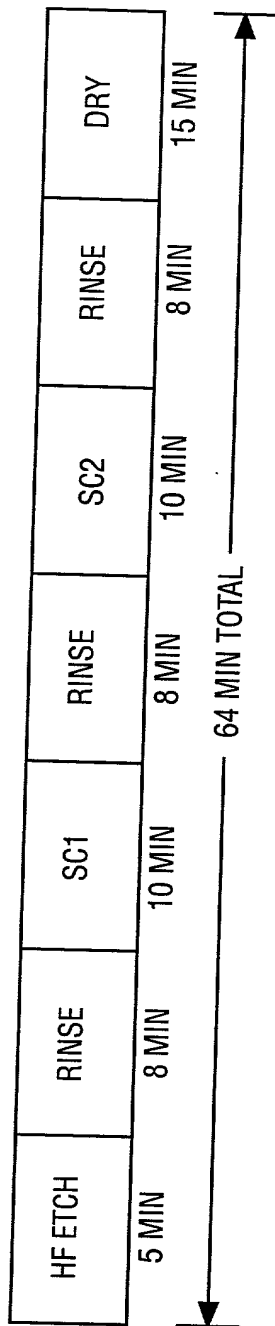


FIG. 1a

SINGLE WAFER CLEANING TOOL SINGLE STEP CLEAN
OXIDE ETCH + HYDROPHILIC CLEAN

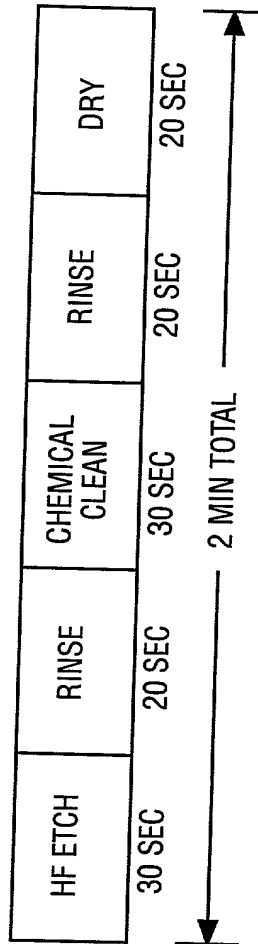


FIG. 1b

$$\begin{array}{c} \text{O} \\ \parallel \\ \text{:}\ddot{\text{O}}-\text{C}-\text{CH}_2 \\ \diagdown \\ (-)\text{:N}-\text{CH}_2-\text{CH}_2-\text{N:}(-) \\ \diagup \\ \text{CH}_2-\text{C}-\ddot{\text{O}} \\ \parallel \\ \text{O} \end{array} \quad \begin{array}{c} \text{O} \\ \parallel \\ \text{CH}_2-\text{C}-\ddot{\text{O}} \\ \diagup \\ \text{N:}(-) \\ \diagdown \\ \text{CH}_2-\text{C}-\ddot{\text{O}} \\ \parallel \\ \text{O} \end{array}$$

BINDS METAL IONS

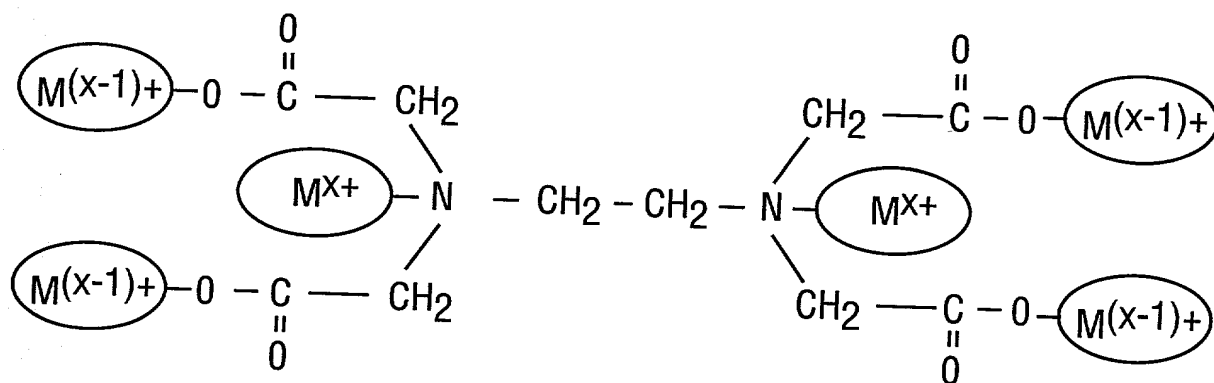
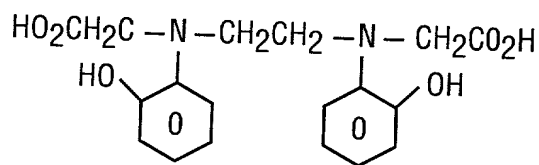
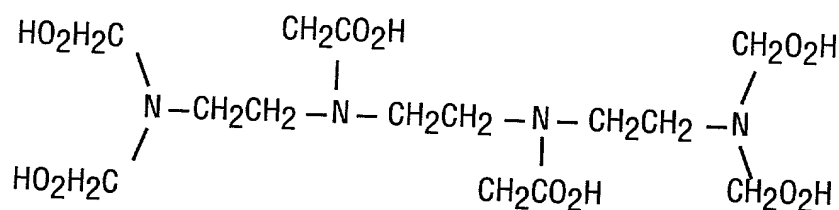


FIG. 2b



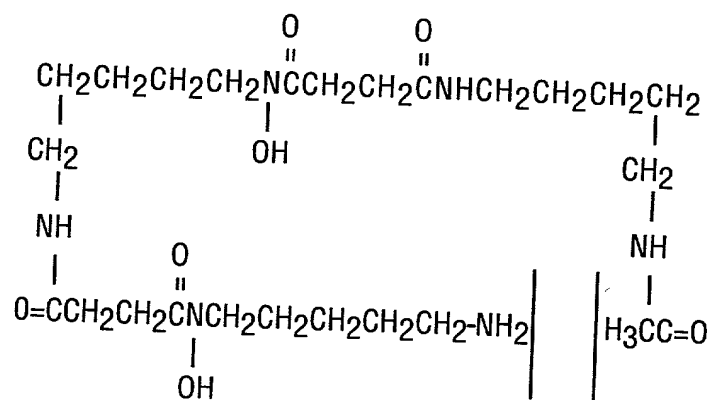
(HPED)

FIG. 3a



(TTHA)

FIG. 3b



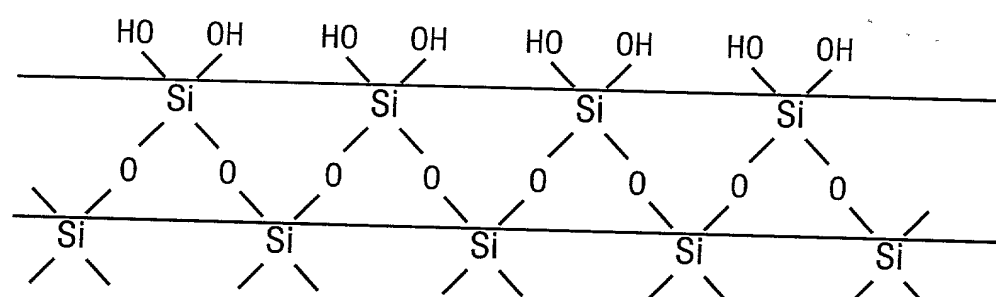
DESFERRIFERRIOXAMIN B

FIG. 3c

O=C(N)CCCNC(=O)C1C(C)C(C1)CNC(=O)CCCNC(=O)O

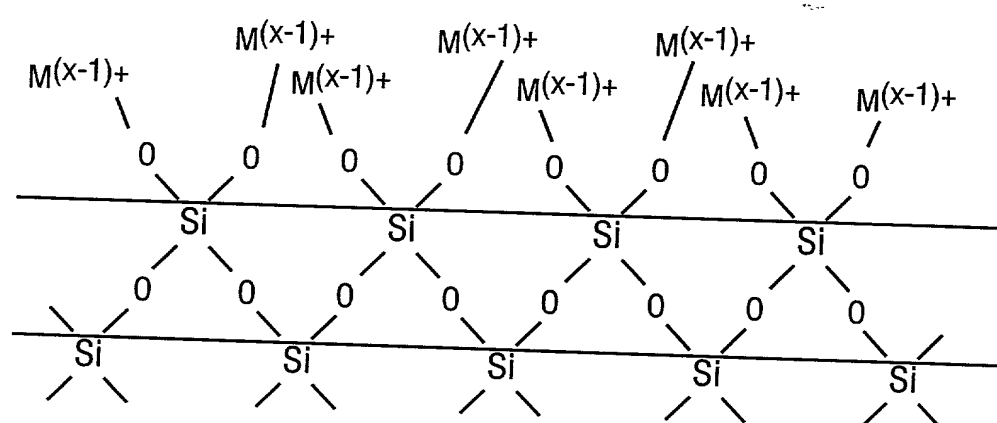
FIG. 3d

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HYDROXIDE
TERMINATED SiO_2 FILM

FIG. 4a



CHEMISORPTION

FIG. 4b

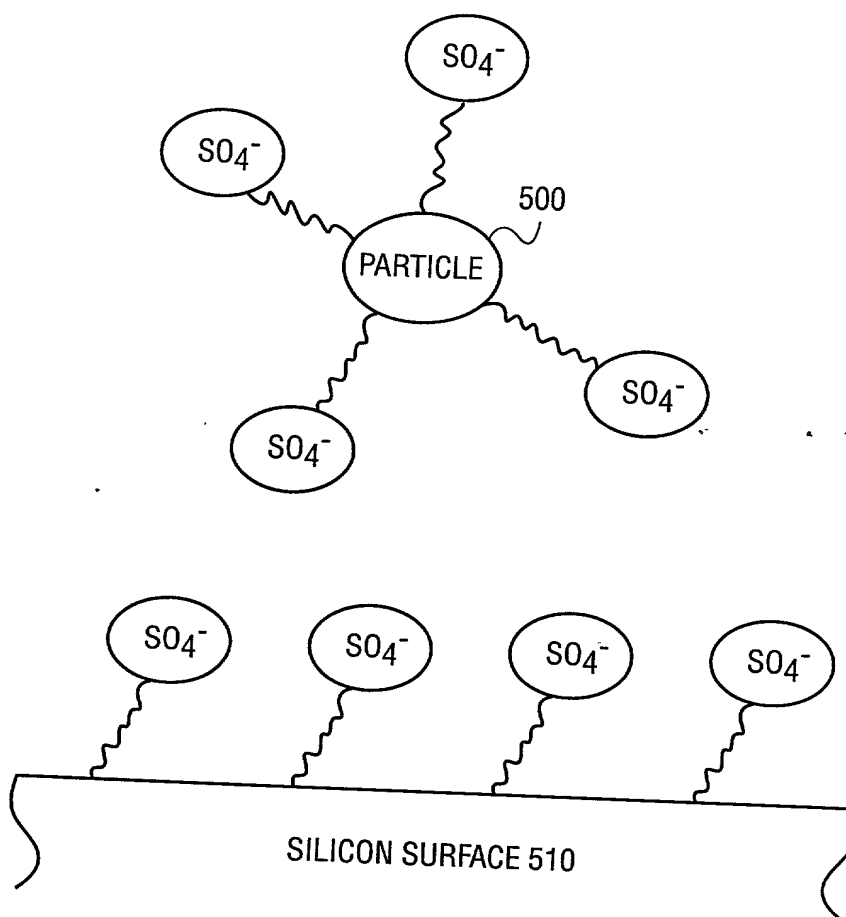


FIG. 5

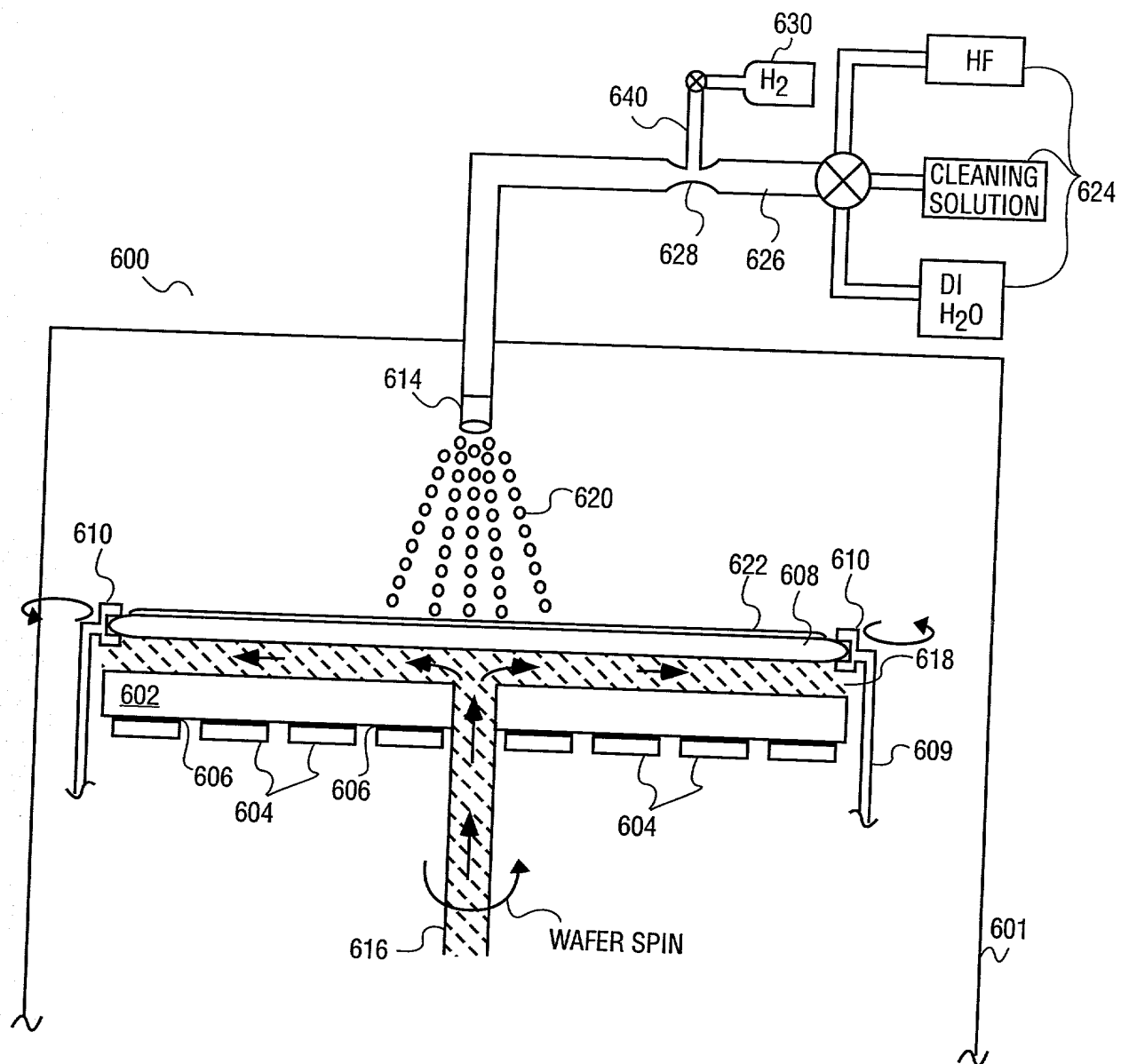


FIG. 6a

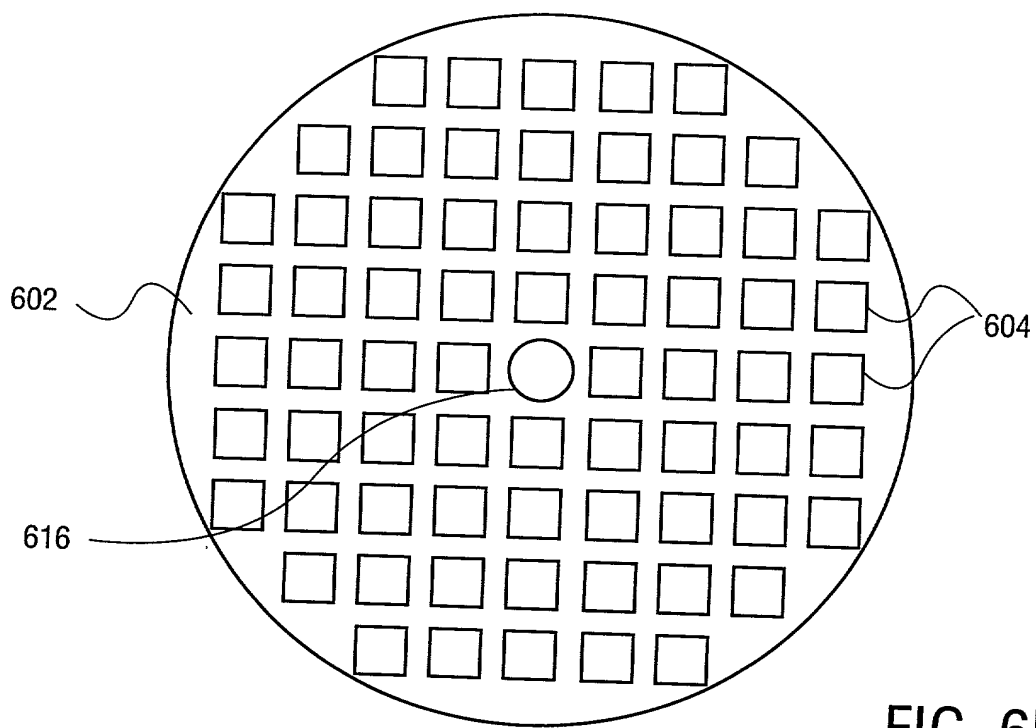


FIG. 6b

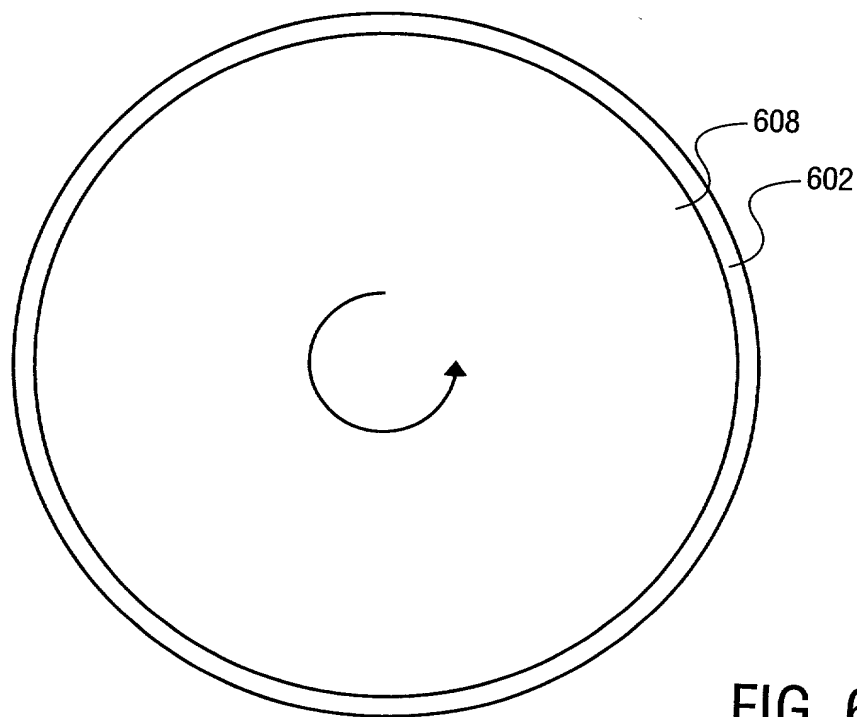


FIG. 6c

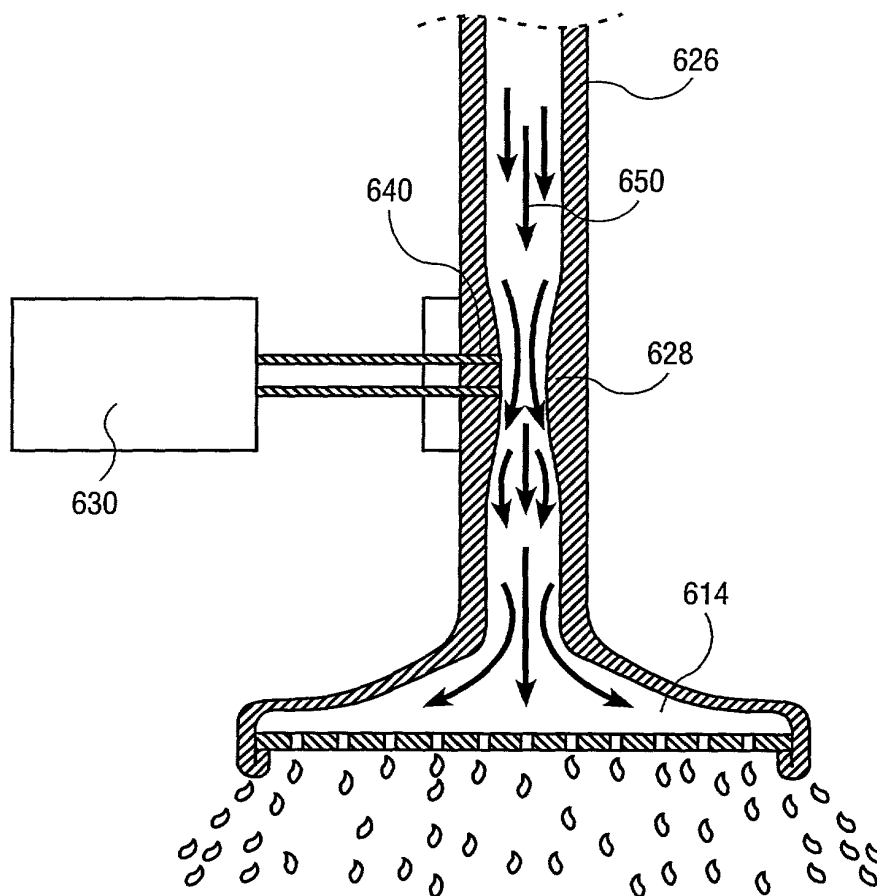


FIG. 6d

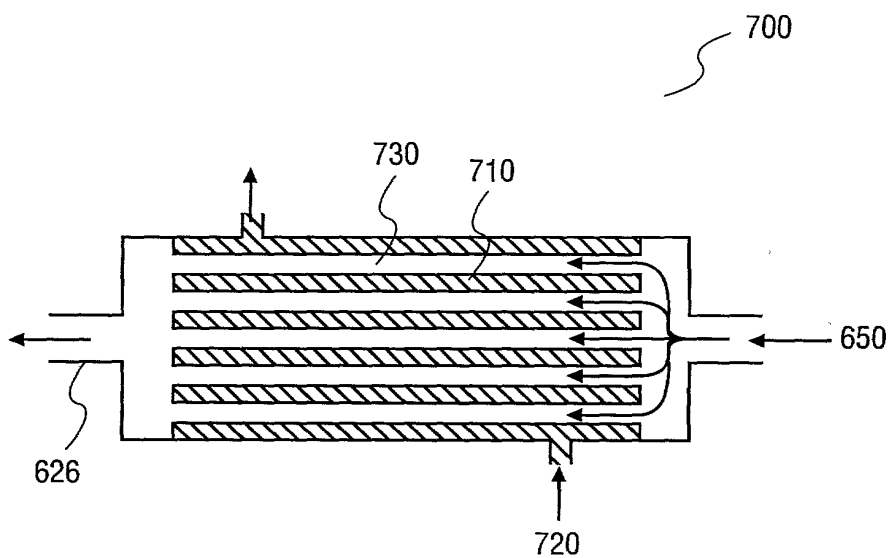


FIG. 7a

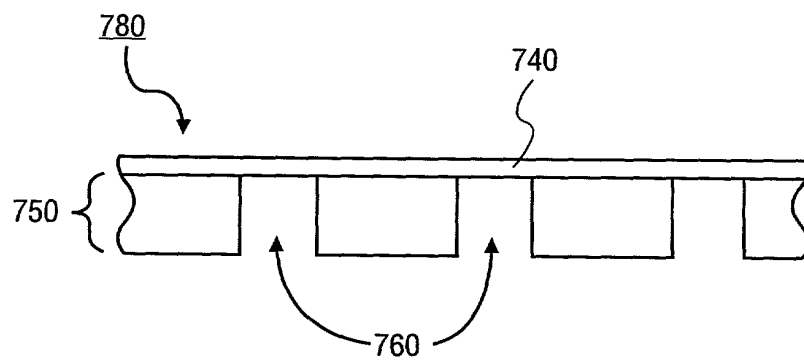


FIG. 7b

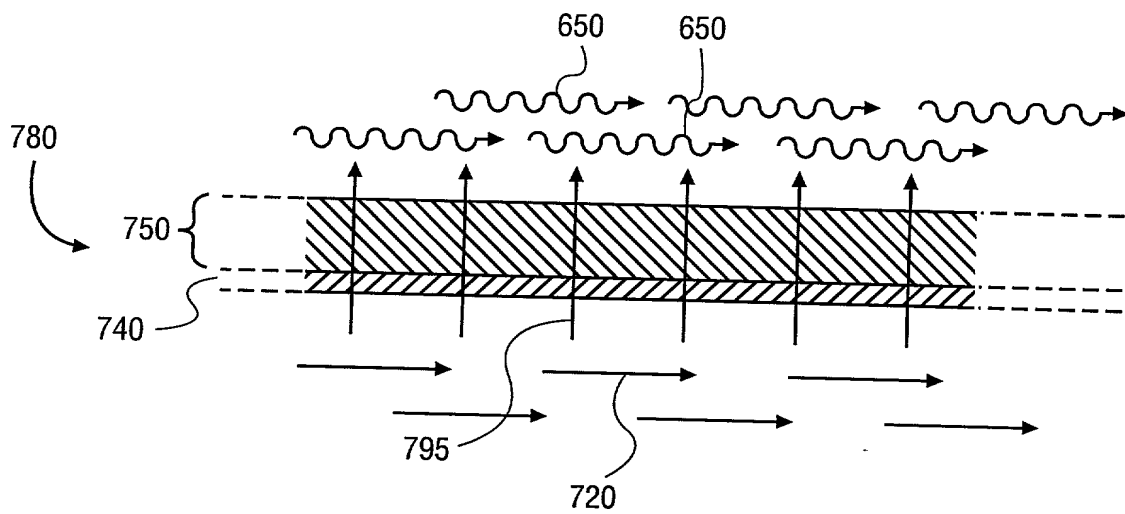


FIG. 7c

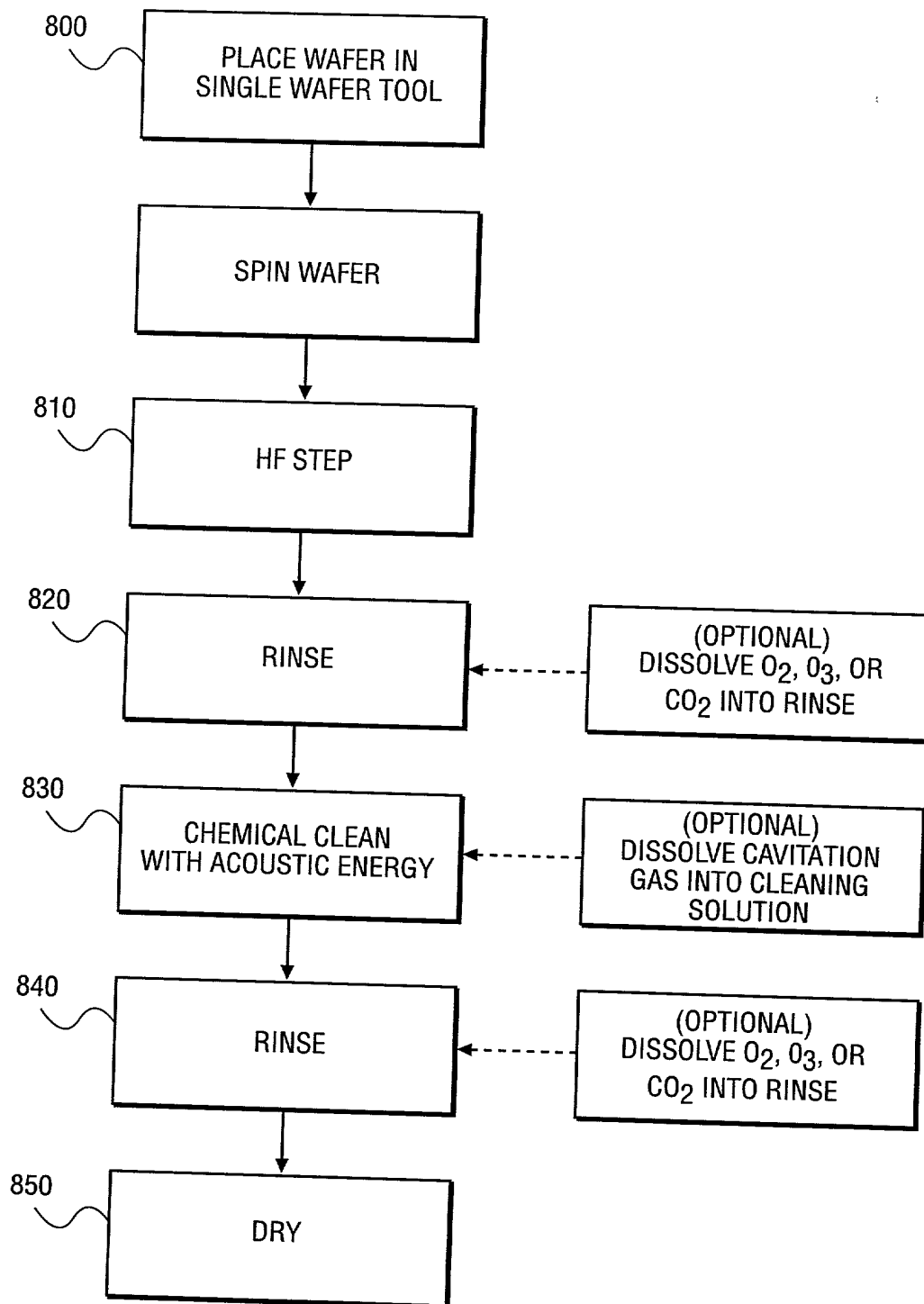


FIG. 8

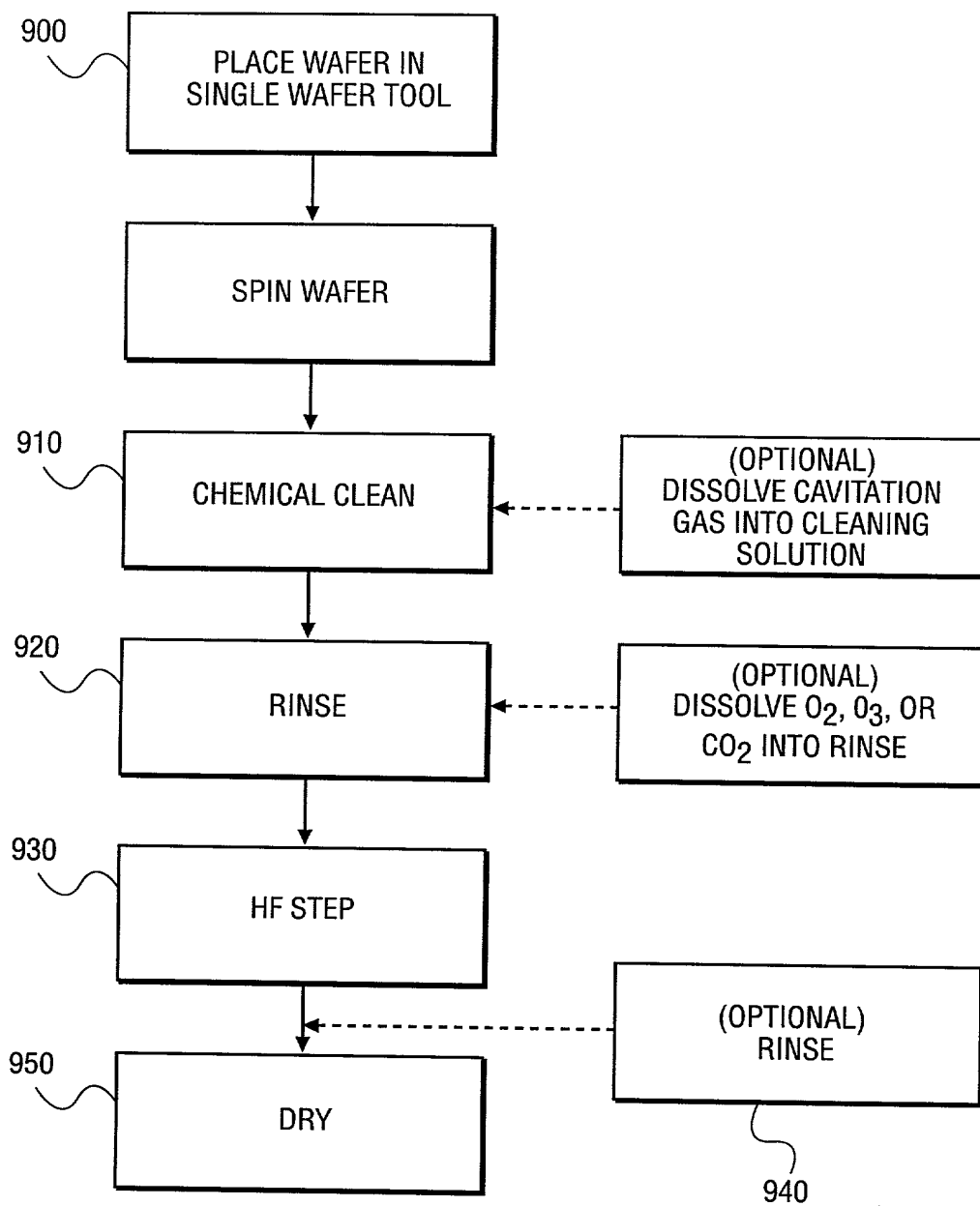


FIG. 9

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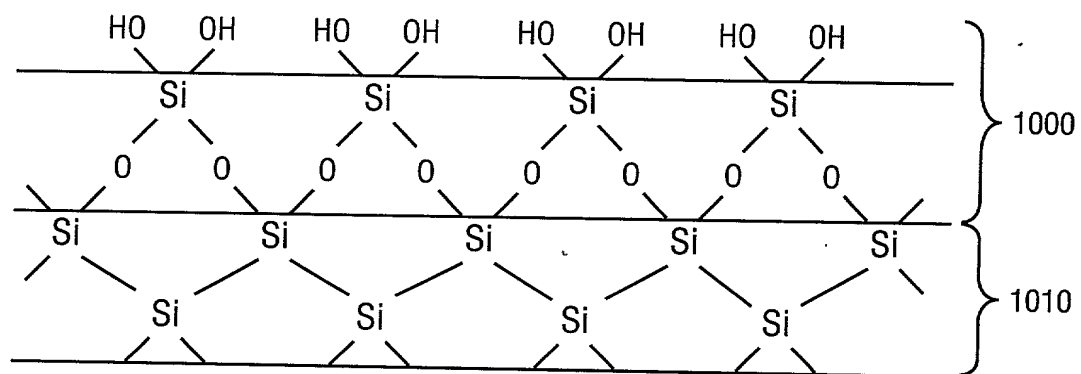
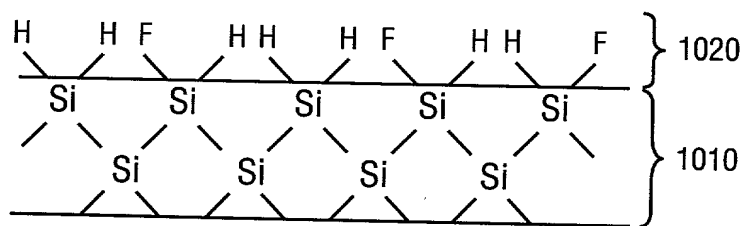


FIG. 10a



HYDROPHOLIC SURFACE

FIG. 10b

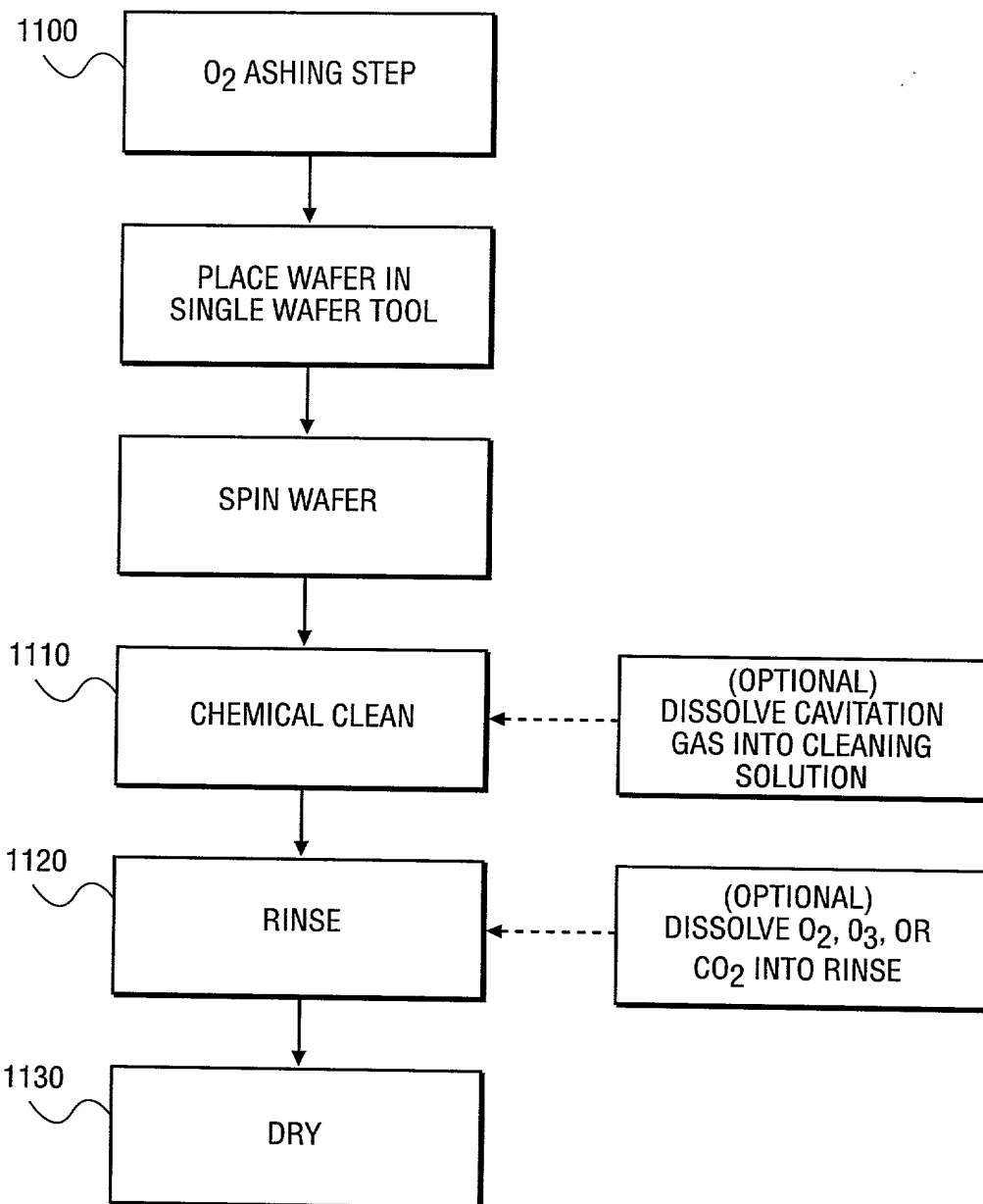


FIG. 11

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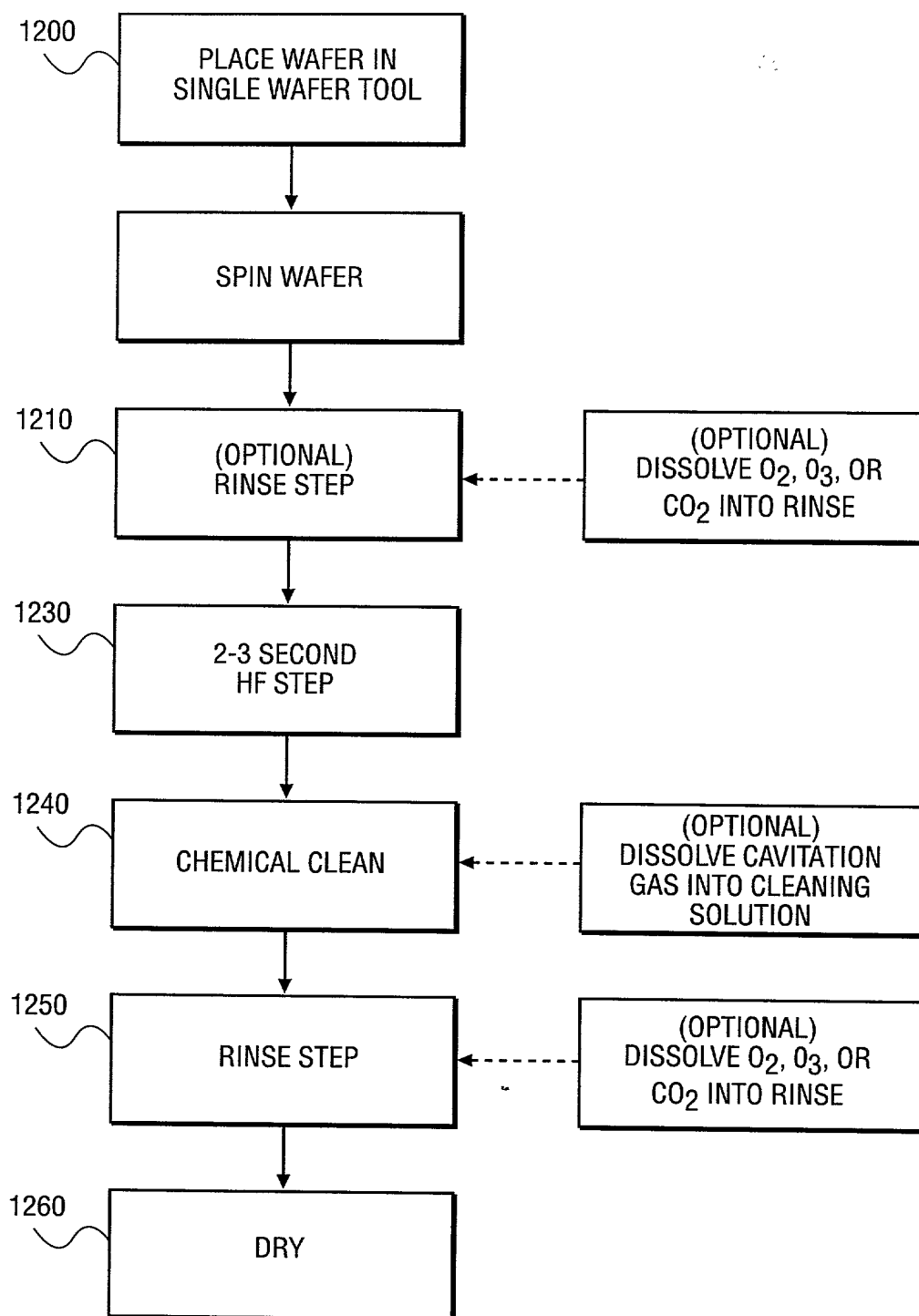


FIG. 12

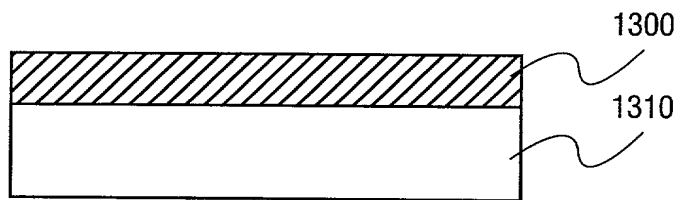


FIG. 13a

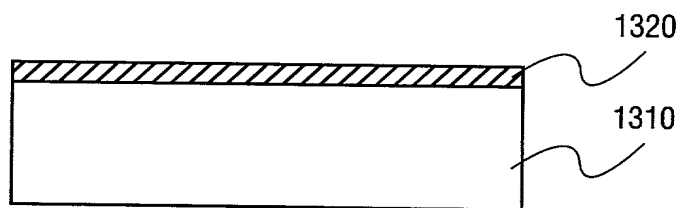


FIG. 13b